EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S22	359	packag$3 with stack$3 with lid	USPAT; EPO; JPO	OR	ON	2006/02/21 15:14
S23	44	packag$3 same stack$3 with lid with (ic die chip semiconductor)	USPAT; EPO; JPO	OR	ON	2006/02/21 15:50
S24	3	packag$3 with shield$3 and stack$3 with lid with (ic die chip semiconductor)	USPAT; EPO; JPO	OR	ON	2006/02/21 15:50
S25	20	packag$3 same shield$3 and stack$4 with (cover cap lid) with (ic die chip semiconductor)	USPAT; EPO; JPO	OR	ON	2006/02/21 15:53
S26	70995	"438"/$ packag$3 and stack$4 with (cover cap lid) with (ic die chip semiconductor)	USPAT; EPO; JPO	OR	ON	2006/02/21 15:54
S27	103	"438"/$ and packag$3 and stack$4 with (cover cap lid) with (ic die chip semiconductor)	USPAT; EPO; JPO	OR	ON	2006/02/21 18:13
S28	3	("5579207" | "6493229" | "6525942").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/21 15:58
S29	29	("5523622" | "5572405" | "5598321" | "5705851" | "5719440" | "5724232" | "5729432" | "5793118" | "5818698" | "5854507" | "5866953" | "5903052" | "5909057" | "5936305" | "5959353" | "5959356" | "6025648" | "6081037" | "6104093" | "6111313" | "6201301" | "6248951" | "6255143" | "6265772" | "6274929" | "6297960" | "6303997" | "6331939" | "6381141").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/21 15:58
S30	3	("5552633"|"5763939"|"6445591").PN.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/02/21 16:03
S31	14	("5523622" | "5572405" | "5598321" | "5705851" | "5719440" | "5724232" | "5729432" | "5793118" | "5818698" | "5854507" | "5866953" | "5903052" | "5936305" | "5959356").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/21 16:26
S32	49	("6122171").URPN.	USPAT	OR	ON	2006/02/21 16:26
S33	387	"438"/$ and stack$4 near4 (ic die chip semiconductor) same (cover cap lid)	USPAT; EPO; JPO	OR	ON	2006/02/21 18:21
S34	111	S33 and (reduc$3 minimiz$3) with (size weigth shape dimension)	USPAT; EPO; JPO	OR	ON	2006/02/21 18:16

S35	3	("5471011" | "5757075" | "5773879").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/21 18:19
S36	4	("6091142").URPN.	USPAT	OR	ON	2006/02/21 18:20
S37	51	"257"/$ and stack$4 near4 (ic die chip semiconductor) same (cover cap lid) and (reduc$3 minimiz$3) with (size weigth shape dimension) not S34	USPAT; EPO; JPO	OR	ON	2006/02/21 18:40
S38	21	("4278991" | "4460825" | "4996587" | "5048179" | "5223741" | "5280192" | "5331203" | "5357056" | "5384689" | "5689091" | "5723900" | "5723901" | "5723907" | "5736780" | "5736981" | "5739585" | "5801439" | "5811879" | "5835988" | "5895970" | "5939782").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/21 18:23
S39	309	"257"/$ and stack$4 near4 (ic die chip semiconductor) same (cover cap lid) and "438"/$	USPAT; EPO; JPO	OR	ON	2006/02/21 18:40
S40	3	("5579207" | "6493229" | "6525942").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/21 18:42
S41	3	("6316289" | "6352879" | "6620649").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/21 18:44
S42	4	("4807021" | "5952714" | "5973337" | "6049074").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/21 18:45